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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	32256
Number of Logic Elements/Cells	-
Total RAM Bits	294912
Number of I/O	684
Number of Gates	2000000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-55°C ~ 125°C (TA)
Package / Case	1152-BGA
Supplier Device Package	1152-FPBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ax2000-fg1152m

Table 2-5 • Different Components Contributing to the Total Power Consumption in Axcelerator Devices

Component	Definition	Device Specific Value (in µW/MHz)				
		AX125	AX250	AX500	AX1000	AX2000
P1	Core tile HCLK power component	33	49	71	130	216
P2	R-cell power component	0.2	0.2	0.2	0.2	0.2
P3	HCLK signal power dissipation	4.5	4.5	9	13.5	18
P4	Core tile RCLK power component	33	49	71	130	216
P5	R-cell power component	0.3	0.3	0.3	0.3	0.3
P6	RCLK signal power dissipation	6.5	6.5	13	19.5	26
P7	Power dissipation due to the switching activity on the R-cell	1.6	1.6	1.6	1.6	1.6
P8	Power dissipation due to the switching activity on the C-cell	1.4	1.4	1.4	1.4	1.4
P9	Power component associated with the input voltage	10	10	10	10	10
P10	Power component associated with the output voltage	See table Per pin contribution				
P11	Power component associated with the read operation in the RAM block	25	25	25	25	25
P12	Power component associated with the write operation in the RAM block	30	30	30	30	30
P13	Core PLL power component	1.5	1.5	1.5	1.5	1.5

Ptotal = Pdc + Pac

P_{dc} = ICCA * VCCA

P_{ac} = $P_{HCLK} + P_{CLK} + P_{R\text{-}cells} + P_{C\text{-}cells} + P_{inputs} + P_{outputs} + P_{memory} + P_{PLL}$

P_{HCLK} = (P1 + P2 * s + P3 * sqrt[s]) * Fs

s = the number of R-cells clocked by this clock

Fs = the clock frequency

PCLK = (P4 + P5 * s + P6 * sqrt[s]) * Fs

s = the number of R-cells clocked by this clock

Fs = the clock frequency

PR-cells = P7 * ms * Fs

ms = the number of R-cells switching at each Fs cycle

Fs = the clock frequency

PC-cells = P8 * mc * Fs

mc = the number of C-cells switching at each Fs cycle

Fs = the clock frequency

Pinputs = P9 * pi * Fpi

pi = the number of inputs

F_{pi} = the average input frequency

Thermal Characteristics

Introduction

The temperature variable in Microsemi's Designer software refers to the junction temperature, not the ambient temperature. This is an important distinction because dynamic and static power consumption cause the chip junction temperature to be higher than the ambient temperature. EQ 1 can be used to calculate junction temperature.

$$T_J = \text{Junction Temperature} = \Delta T + T_a$$

EQ 1

Where:

T_a = Ambient Temperature

ΔT = Temperature gradient between junction (silicon) and ambient

$$\Delta T = \theta_{ja} * P$$

EQ 2

Where:

P = Power

θ_{ja} = Junction to ambient of package. θ_{ja} numbers are located under Table 2-6 on page 2-7.

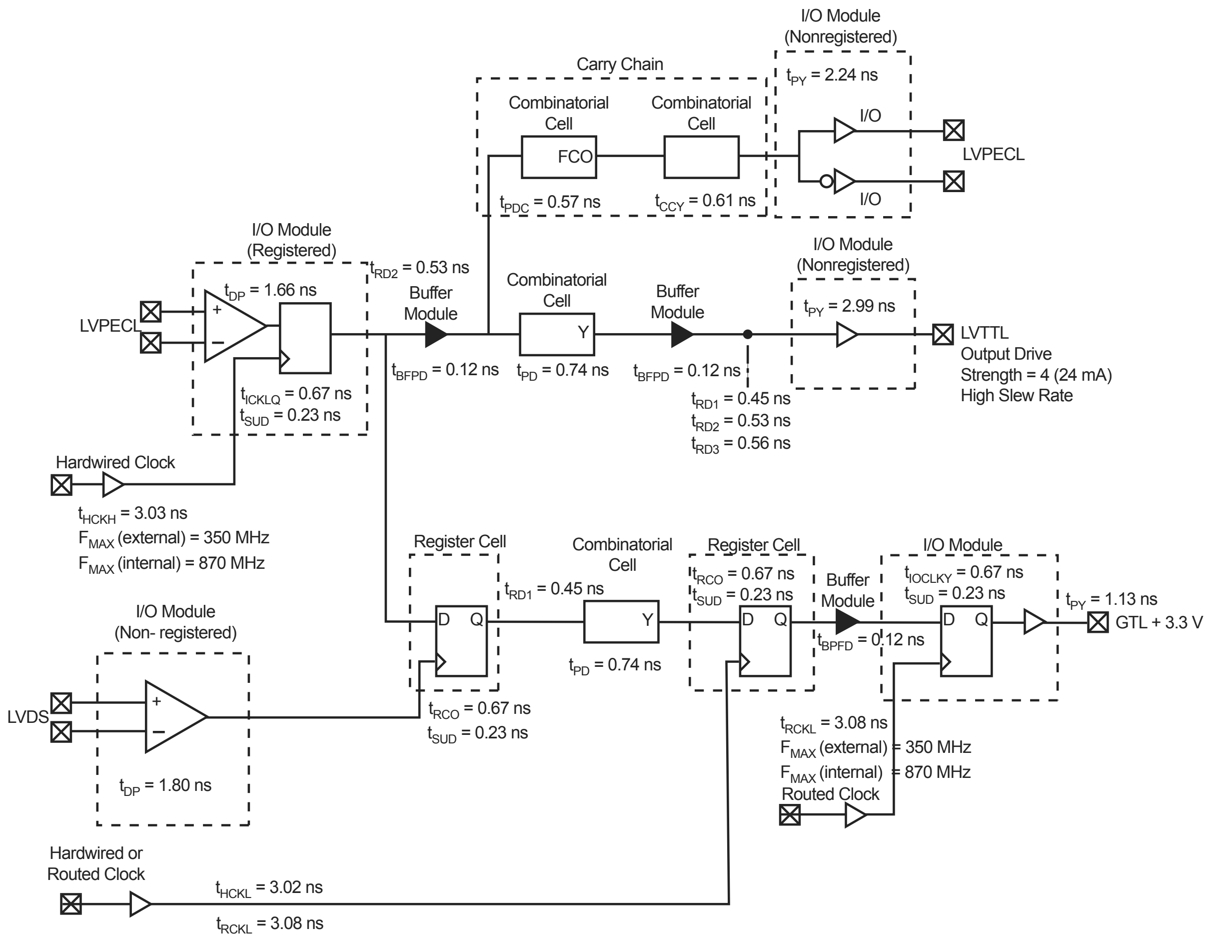
Package Thermal Characteristics

The device junction-to-case thermal characteristic is θ_{jc}, and the junction-to-ambient air characteristic is θ_{ja}. The thermal characteristics for θ_{ja} are shown with two different air flow rates. θ_{jc} values are provided for reference. The absolute maximum junction temperature is 125°C.

The maximum power dissipation allowed for commercial- and industrial-grade devices is a function of θ_{ja}. A sample calculation of the absolute maximum power dissipation allowed for an 896-pin FBGA package at commercial temperature and still air is as follows:

$$\text{Maximum Power Allowed} = \frac{\text{Max. junction temp. } (^\circ C) - \text{Max. ambient temp. } (^\circ C)}{\theta_{ja}(^\circ C/W)} = \frac{125^\circ C - 70^\circ C}{13.6^\circ C/W} = 4.04\ W$$

Timing Model



Note: Worst case timing data for the AX1000, –2 speed grade

Figure 2-1 • **Worst Case Timing Data**

Hardwired Clock – Using LVTTL 24 mA High Slew Clock I/O

External Setup

$= (t_{DP} + t_{RD2} + t_{SUD}) - t_{HCKL}$

$= (1.72 + 0.53 + 0.23) - 3.02 = -0.54$ ns

Clock-to-Out (Pad-to-Pad)

$= t_{HCKL} + t_{RCO} + t_{RD1} + t_{PY}$

$= 3.02 + 0.67 + 0.45 + 2.99 = 7.13$ ns

Routed Clock – Using LVTTL 24 mA High Slew Clock I/O

External Setup

$= (t_{DP} + t_{RD2} + t_{SUD}) - t_{RCKH}$

$= (1.72 + 0.53 + 0.23) - 3.13 = -0.65$ ns

Clock-to-Out (Pad-to-Pad)

$= t_{RCKH} + t_{RCO} + t_{RD1} + t_{PY}$

$= 3.13 + 0.67 + 0.45 + 3.03 = 7.24$ ns

User I/O Naming Conventions

Due to the complex and flexible nature of the Axcelerator family's user I/Os, a naming scheme is used to show the details of the I/O. The naming scheme explains to which bank an I/O belongs, as well as the pairing and pin polarity for differential I/Os (Figure 2-7).

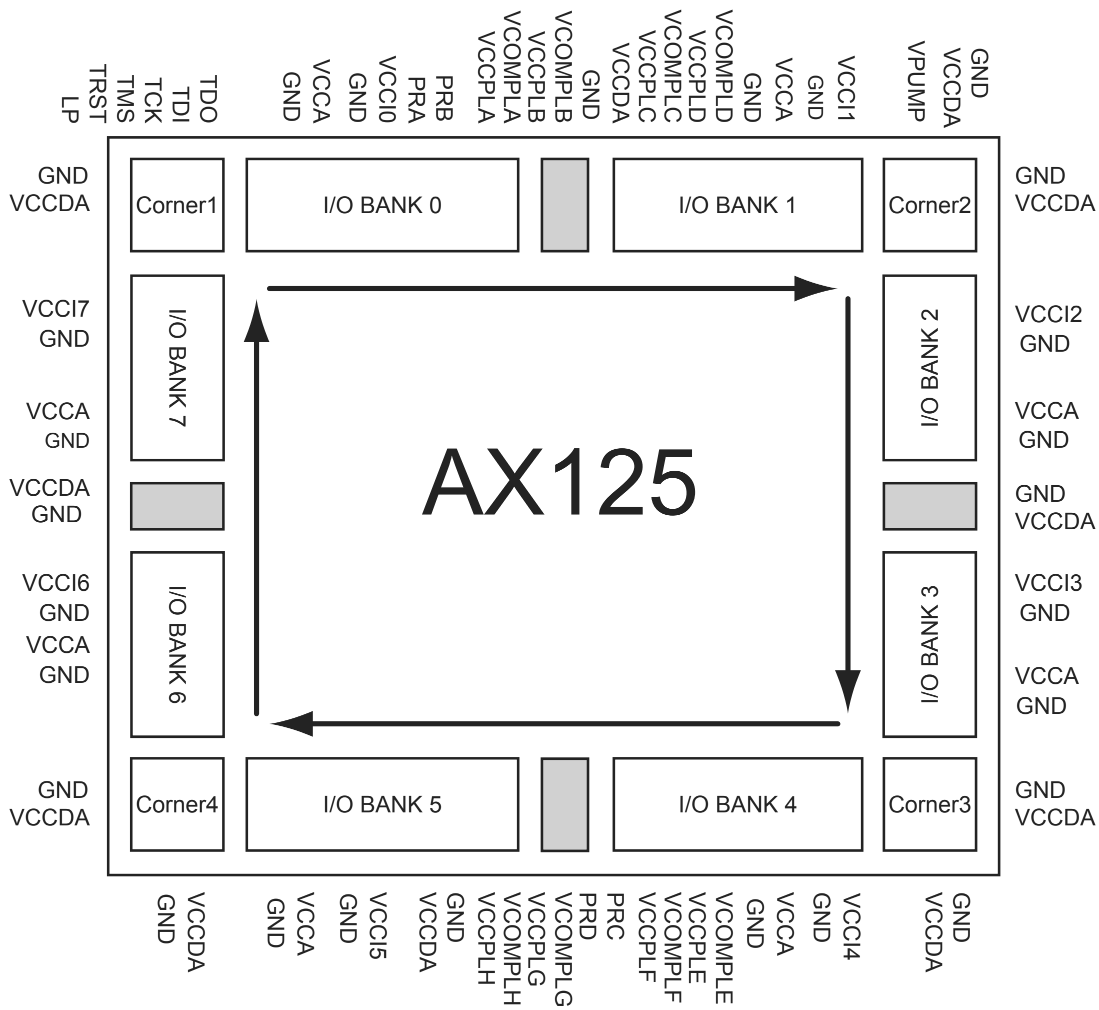
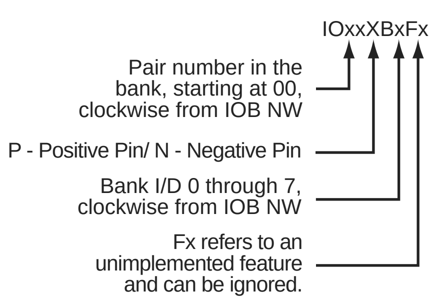


Figure 2-7 • **I/O Bank and Dedicated Pin Layout**



Examples:

IO12PB1F1 is the positive pin of the thirteenth pair of the first I/O bank (IOB NE). IO12PB1 combined with IO12NB1 form a differential pair.

For those I/Os that can be employed either as a user I/O or as a special function, the following nomenclature is used:

IOxxXBxFx/special_function_name

IOxxPB1Fx/xCLKx this pin can be configured as a clock input or as a user I/O.

Figure 2-8 • **General Naming Schemes**

Table 2-36 **• 3.3 V PCI-X I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
3.3 V PCI-X Output Module Timing								
t_{DP}	Input Buffer		1.57		1.79		2.10	ns
t_{PY}	Output Buffer		2.10		2.40		2.82	ns
t_{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		1.61		1.62		1.63	ns
t_{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		1.59		1.60		1.61	ns
t_{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		2.65		3.02		3.55	ns
t_{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		3.11		3.55		4.17	ns
t_{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t_{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

PLLRCLK and PLLHCLK

PLLRCLK (PLLHCLK) is used to drive global resource CLK (HCLK) from a PLL (Figure 2-44).

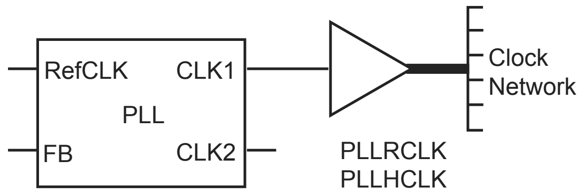


Figure 2-44 • **PLLRCLK and PLLHCLK**

Using Global Resources with PLLs

Each global resource has an associated PLL at its root. For example, PLLA can drive HCLKA, PLLE can drive CLKE, etc. (Figure 2-45).

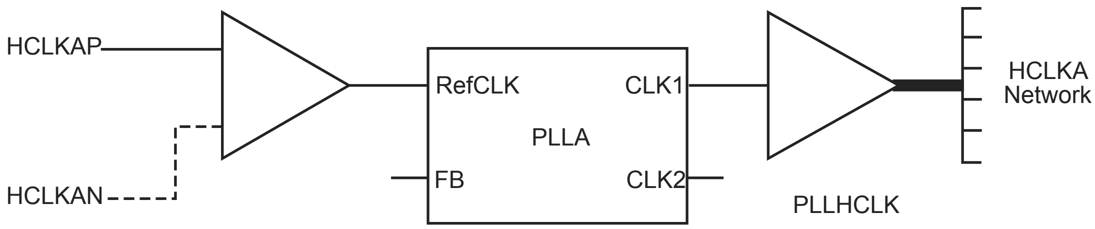


Figure 2-45 • **Example of HCLKA Driven from a PLL with External Clock Source**

In addition, each clock pin of the package can be used to drive either its associated global resource or PLL. For example, package pins CLKEP and CLKEN can drive either the RefCLK input of PLLE or CLKE.

There are two macros required when interfacing the embedded PLLs with the global resources: PLLINT and PLLOUT.

PLLINT

This macro is used to drive the RefCLK input of the PLL internally from user signals.

PLLOUT

This macro is used to connect either the CLK1 or CLK2 output of a PLL to the regular routing network (Figure 2-46).

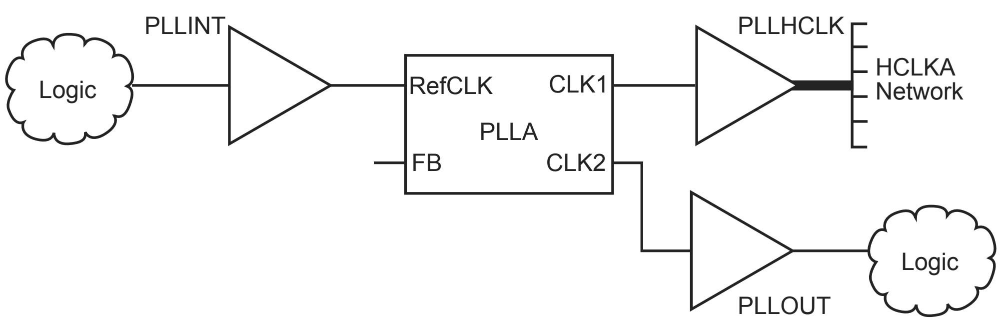


Figure 2-46 • **Example of PLLINT and PLLOUT Usage**

Table 2-93 • Sixteen RAM Blocks Cascaded
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Write Mode								
t_{WDASU}	Write Data Setup vs. WCLK		16.54		18.84		22.15	ns
t_{WDAHD}	Write Data Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WADSU}	Write Address Setup vs. WCLK		16.54		18.84		22.15	ns
t_{WADHD}	Write Address Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WENSU}	Write Enable Setup vs. WCLK		16.54		18.84		22.15	ns
t_{WENHD}	Write Enable Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WCKH}	WCLK Minimum High Pulse Width	0.75		0.75		0.75		ns
t_{WCLK}	WCLK Minimum Low Pulse Width	13.40		13.40		13.40		ns
t_{WCKP}	WCLK Minimum Period	14.15		14.15		14.15		ns
Read Mode								
t_{RADSU}	Read Address Setup vs. RCLK		18.13		20.65		24.27	ns
t_{RADHD}	Read Address Hold vs. RCLK		0.00		0.00		0.00	ns
t_{RENSU}	Read Enable Setup vs. RCLK		18.13		20.65		24.27	ns
t_{RENHD}	Read Enable Hold vs. RCLK		0.00		0.00		0.00	ns
$t_{RCK2RD1}$	RCLK-To-OUT (Pipelined)		12.08		13.76		16.17	ns
$t_{RCK2RD2}$	RCLK-To-OUT (Non-Pipelined)		12.83		14.62		17.18	ns
t_{RCLKH}	RCLK Minimum High Pulse Width	0.73		0.73		0.73		ns
t_{RCLKL}	RCLK Minimum Low Pulse Width	14.41		14.41		14.41		ns
t_{RCKP}	RCLK Minimum Period	15.14		15.14		15.14		ns

Note: Timing data for these sixteen cascaded RAM blocks uses a depth of 65,536. For all other combinations, use Microsemi's timing software.

Glitch Elimination

An analog filter is added to each FIFO controller to guarantee glitch-free FIFO-flag logic.

Overflow and Underflow Control

The counter MSB keeps track of the difference between the read address (RA) and the write address (WA). The EMPTY flag is set when the read and write addresses are equal. To prevent underflow, the write address is double-sampled by the read clock prior to comparison with the read address (part A in Figure 2-64). To prevent overflow, the read address is double-sampled by the write clock prior to comparison to the write address (part B in Figure 2-64).

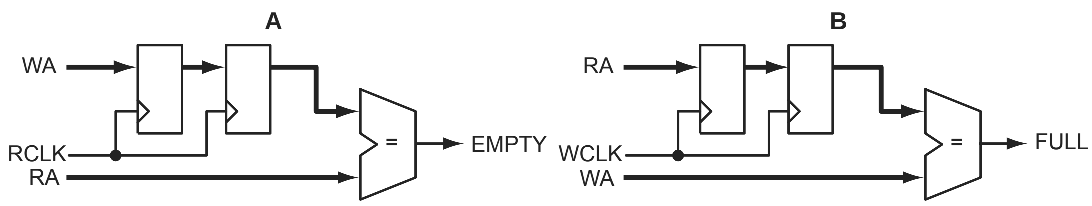


Figure 2-64 **• Overflow and Underflow Control**

FIFO Configurations

Unlike the RAM, the FIFO's write width and read width cannot be specified independently. For the FIFO, the write and read widths must be the same. The WIDTH pins are used to specify one of six allowable word widths, as shown in Table 2-96.

Table 2-96 **• FIFO Width Configurations**

WIDTH(2:0)	W x D
000	1 x 4k
001	2 x 2k
010	4 x 1k
011	9 x 512
100	18 x 256
101	36 x 128
11x	reserved

The DEPTH pins allow RAM cells to be cascaded to create larger FIFOs. The four pins allow depths of 2, 4, 8, and 16 to be specified. Table 2-86 on page 2-87 describes the FIFO depth options for various data width and memory blocks.

Interface

Figure 2-65 on page 2-99 shows a logic block diagram of the Axcelerator FIFO module.

Cascading FIFO Blocks

FIFO blocks can be cascaded to create deeper FIFO functions. When building larger FIFO blocks, if the word width can be fractured in a multi-bit FIFO, the fractured word configuration is recommended over a cascaded configuration. For example, 256x36 can be configured as two blocks of 256x18. This should be taken into account when building the FIFO blocks manually. However, when using SmartGen, the user only needs to specify the depth and width of the necessary FIFO blocks. SmartGen automatically configures these blocks to optimize performance.

mode if desired. Please note, if the I/O bank is not disabled, differential I/Os belonging to the I/O bank will still consume normal power, even when operating in the low power mode.

The Axcelerator device will resume normal operation 10µs after the LP pin is pulled Low.

To further reduce power consumption, the internal charge pump can be bypassed and an external power supply voltage can be used instead. This saves the internal charge-pump operating current, resulting in no DC current draw. The Axcelerator family devices have a dedicated "V_{PUMP}" pin that can be used to access an external charge pump device. In normal chip operation, when using the internal charge pump, V_{PUMP} should be tied to GND. When the voltage level on V_{PUMP} is set to 3.3V, the internal charge pump is turned off, and the V_{PUMP} voltage will be used as the charge pump voltage. Adequate voltage regulation (i.e. high drive, low output impedance, and good decoupling) should be used at V_{PUMP}.

In addition, any PLL in use can be powered down to further reduce power consumption. This can be done with the PowerDown pin driven Low. Driving this pin High restarts the PLL with the output clock(s) being stable once lock is restored.

JTAG

Axcelerator offers a JTAG interface that is compliant with the IEEE 1149.1 standard. The user can employ the JTAG interface for probing a design and performing any JTAG Public Instructions as defined in the Table 2-103.

Table 2-103 **• JTAG Instruction Code**

Instruction (IR4:IR0)	Binary Code
Extest	00000
Preload / Sample	00001
Intest	00010
USERCODE	00011
IDCODE	00100
HIGHZ	01110
CLAMP	01111
Diagnostic	10000
Reserved	All others
Bypass	11111

Interface

The interface consists of four inputs: Test Mode Select (TMS), Test Data In (TDI), Test Clock (TCK), TAP Controller Reset (TRST), and an output, Test Data Out (TDO). TMS, TDI, and TRST have on-chip pull-up resistors.

TRST

TRST (Test-Logic Reset) is an active-low, asynchronous reset signal to the TAP controller. The TRST input can be used to reset the Test Access Port (TAP) Controller to the TRST state. The TAP Controller can be held at this state permanently by grounding the TRST pin. To hold the JTAG TAP controller in the TRST state, it is recommended to connect TRST to ground via a 1 kΩ resistor.

There is an optional internal pull-up resistor available for the TRST input that can be set by the user at programming. Care should be exercised when using this option in combination with an external tie-off to ground.

An on-chip power-on-reset (POWRST) circuit is included. POWRST has the same function as "TRST," but it only occurs at power-up or during recovery from a VCCA and/or VCCDA voltage drop.

throughout the fabric of the device and may be programmed by the user to thwart attempts to reverse engineer the device by attempting to exploit either the programming or probing interfaces. Both invasive and noninvasive attacks against an Axcelerator device that access or bypass these security fuses will destroy access to the rest of the device. (refer to the *Design Security in Nonvolatile Flash and Antifuse FPGAs* white paper).

Look for this symbol to ensure your valuable IP is protected with highest level of security in the industry.

Figure 2-69 • **FuseLock Logo**

To ensure maximum security in Axcelerator devices, it is recommended that the user program the device security fuse (SFUS). When programmed, the Silicon Explorer II testing probes are disabled to prevent internal probing, and the programming interface is also disabled. All JTAG public instructions are still accessible by the user.

For more information, refer to the *Implementation of Security in Actel Antifuse FPGAs* application note.

Global Set Fuse

The Global Set Fuse determines if all R-cells and I/O registers (InReg, OutReg, and EnReg) are either cleared or preset by driving the GCLR and GPSET inputs of all R-cells and I/O Registers (Figure 2-31 on page 2-58). Default setting is to clear all registers (GCLR = 0 and GPSET =1) at device power-up. When the GBSETFUS option is checked during FUSE file generation, all registers are preset (GCLR = 1 and GPSET= 0). A local CLR or PRESET will take precedence over this setting. Both pins are pulled High during normal device operation. For use details, see the Libero IDE online help.

Silicon Explorer II Probe Interface

Silicon Explorer II is an integrated hardware and software solution that, in conjunction with the Designer tools, allows users to examine any of the internal nets (except I/O registers) of the device while it is operating in a prototype or a production system. The user can probe up to four nodes at a time without changing the placement and routing of the design and without using any additional device resources. Highlighted nets in Designer’s ChipPlanner can be accessed using Silicon Explorer II in order to observe their real time values.

Silicon Explorer II's noninvasive method does not alter timing or loading effects, thus shortening the debug cycle. In addition, Silicon Explorer II does not require relayout or additional MUXes to bring signals out to external pins, which is necessary when using programmable logic devices from other suppliers. By eliminating multiple place-and-route program cycles, the integrity of the design is maintained throughout the debug process.

Each member of the Axcelerator family has four external pads: PRA, PRB, PRC, and PRD. These can be used to bring out four probe signals from the Axcelerator device (note that the AX125 only has two probe signals that can be observed: PRA and PRB). Each core tile has up to two probe signals. To disallow probing, the SFUS security fuse in the silicon signature has to be programmed (see "Special Fuses" on page 2-108).

Silicon Explorer II connects to the host PC using a standard serial port connector. Connections to the circuit board are achieved using a nine-pin D-Sub connector (Figure 1-9 on page 1-7). Once the design has been placed-and-routed, and the Axcelerator device has been programmed, Silicon Explorer II can be connected and the Explorer software can be launched.

Silicon Explorer II comes with an additional optional PC hosted tool that emulates an 18-channel logic analyzer. Four channels are used to monitor four internal nodes, and 14 channels are available to probe external signals. The software included with the tool provides the user with an intuitive interface that allows for easy viewing and editing of signal waveforms.

Programming

Device programming is supported through the Silicon Sculptor II, a single-site, robust and compact device programmer for the PC. Up to four Silicon Sculptor IIs can be daisy-chained and controlled from a single PC host. With standalone software for the PC, Silicon Sculptor II is designed to allow concurrent programming of multiple units from the same PC when daisy-chained.

Silicon Sculptor II programs devices independently to achieve the fastest programming times possible. Each fuse is verified by Silicon Sculptor II to ensure correct programming. Furthermore, at the end of programming, there are integrity tests that are run to ensure that programming was completed properly. Not only does it test programmed and nonprogrammed fuses, Silicon Sculptor II also provides a self-test to test its own hardware extensively.

Programming an Axcelerator device using Silicon Sculptor II is similar to programming any other antifuse device. The procedure is as follows:

1. Load the *.AFM file.
2. Select the device to be programmed.
3. Begin programming.

When the design is ready to go to production, Microsemi offers device volume-programming services either through distribution partners or via our In-House Programming Center.

In addition, BP Microsystems offers multi-site programmers that provide qualified support for Axcelerator devices.

For more details on programming the Axcelerator devices, please refer to the *Silicon Sculptor II User's Guide*.

FG324	
AX125 Function	**Pin Number**
IO50NB4F4/CLKFN	U9
IO50PB4F4/CLKFP	U10
Bank 5	
IO51NB5F5/CLKGN	R8
IO51PB5F5/CLKGP	R9
IO52NB5F5/CLKHN	T7
IO52PB5F5/CLKHP	T8
IO53NB5F5	U6
IO53PB5F5	U7
IO54NB5F5	V8
IO54PB5F5	V9
IO55NB5F5	V6
IO55PB5F5	V7
IO56NB5F5	U4
IO56PB5F5	U5
IO57NB5F5	T4
IO57PB5F5	T5
IO58NB5F5	V4
IO58PB5F5	V5
IO59NB5F5	V2
IO59PB5F5	V3
Bank 6	
IO60NB6F6	P5
IO60PB6F6	P6
IO61NB6F6	T2
IO61PB6F6	U3
IO62NB6F6	T1
IO62PB6F6	U1
IO63NB6F6	P1
IO63PB6F6	R1
IO64NB6F6	R3
IO64PB6F6	P3
IO65NB6F6	P2
IO65PB6F6	R2
IO66NB6F6	M3

FG324	
AX125 Function	**Pin Number**
IO66PB6F6	N3
IO67NB6F6	M2
IO67PB6F6	N2
IO68NB6F6	M1
IO68PB6F6	N1
IO69NB6F6	K4
IO69PB6F6	L4
IO70NB6F6	K1
IO70PB6F6	L1
IO71NB6F6	K3
IO71PB6F6	L3
Bank 7	
IO72NB7F7	H4
IO72PB7F7	J4
IO73NB7F7	K2
IO73PB7F7	L2
IO74NB7F7	H2
IO74PB7F7	H1
IO75NB7F7	H3
IO75PB7F7	J3
IO76NB7F7	F2
IO76PB7F7	G2
IO77NB7F7	F1
IO77PB7F7	G1
IO78NB7F7	D2
IO78PB7F7	E2
IO79NB7F7	F3
IO79PB7F7	G3
IO80NB7F7	E3
IO80PB7F7	E4
IO81NB7F7	D1
IO81PB7F7	E1
IO82NB7F7	D3
IO82PB7F7	C2
IO83NB7F7	B1

FG324	
AX125 Function	**Pin Number**
IO83PB7F7	C1
Dedicated I/O	
VCCDA	F5
GND	A1
GND	A18
GND	B17
GND	B2
GND	C16
GND	C3
GND	E16
GND	F13
GND	F6
GND	G12
GND	G7
GND	H10
GND	H11
GND	H8
GND	H9
GND	J10
GND	J11
GND	J8
GND	J9
GND	K10
GND	K11
GND	K8
GND	K9
GND	L10
GND	L11
GND	L8
GND	L9
GND	M12
GND	M7
GND	N13
GND	N6
GND	R14

FG896	
AX2000 Function	Pin Number
IO180PB4F16	AG24
IO181NB4F17	AK24
IO181PB4F17	AK25
IO182NB4F17	AD22
IO182PB4F17	AC22
IO183NB4F17	AF22
IO183PB4F17	AF23
IO184NB4F17	AE21
IO184PB4F17	AE22
IO185NB4F17	AJ23
IO185PB4F17	AJ24
IO187NB4F17	AH22
IO187PB4F17	AH23
IO188NB4F17	AD21
IO188PB4F17	AC21
IO189PB4F17	AK22
IO190NB4F17	AF20
IO190PB4F17	AF21
IO191NB4F17	AG21
IO191PB4F17	AG22
IO192NB4F17	AE19
IO192PB4F17	AE20
IO195NB4F18	AK21
IO195PB4F18	AJ21
IO196NB4F18	AD19
IO196PB4F18	AD20
IO197NB4F18	AJ20
IO197PB4F18	AK20
IO198NB4F18	AC19
IO198PB4F18	AC20
IO199NB4F18	AG19
IO199PB4F18	AG20
IO200NB4F18	AH19
IO200PB4F18	AH20
IO201NB4F18	AK19

FG896	
AX2000 Function	Pin Number
IO201PB4F18	AJ19
IO202NB4F18	AC18
IO202PB4F18	AB18
IO206NB4F19	AE18
IO206PB4F19	AD18
IO207NB4F19	AJ17
IO207PB4F19	AJ18
IO208NB4F19	AE17
IO208PB4F19	AD17
IO209NB4F19	AK17
IO210NB4F19	AC17
IO210PB4F19	AB17
IO211NB4F19	AJ16
IO211PB4F19	AK16
IO212NB4F19/CLKEN	AG18
IO212PB4F19/CLKEP	AH18
IO213NB4F19/CLKFN	AG16
IO213PB4F19/CLKFP	AG17
Bank 5	
IO214NB5F20/CLKGN	AG14
IO214PB5F20/CLKGP	AG15
IO215NB5F20/CLKHN	AG13
IO215PB5F20/CLKHP	AH13
IO216NB5F20	AB14
IO216PB5F20	AC15
IO217NB5F20	AK15
IO217PB5F20	AJ15
IO218NB5F20	AE14
IO218PB5F20	AD14
IO219NB5F20	AK14
IO219PB5F20	AJ14
IO222NB5F20	AB13
IO222PB5F20	AC14
IO223NB5F21	AJ12
IO223PB5F21	AJ13

FG896	
AX2000 Function	Pin Number
IO225NB5F21	AH11
IO225PB5F21	AH12
IO226NB5F21	AC13
IO226PB5F21	AD13
IO227NB5F21	AE12
IO227PB5F21	AE13
IO228NB5F21	AG11
IO228PB5F21	AG12
IO229NB5F21	AK11
IO229PB5F21	AK12
IO230NB5F21	AC12
IO230PB5F21	AD12
IO232NB5F21	AE11
IO232PB5F21	AF11
IO233NB5F21	AJ10
IO233PB5F21	AJ11
IO234NB5F21	AC11
IO234PB5F21	AD11
IO236NB5F22	AK9
IO236PB5F22	AK10
IO237NB5F22	AG9
IO237PB5F22	AG10
IO238NB5F22	AF9
IO238PB5F22	AF10
IO239NB5F22	AH8
IO239PB5F22	AH9
IO240NB5F22	AC10
IO240PB5F22	AD10
IO242NB5F22	AE9
IO242PB5F22	AE10
IO243NB5F22	AJ7
IO243PB5F22	AJ8
IO244NB5F22	AK6
IO244PB5F22	AK7
IO245NB5F23	AF8

FG896	
AX2000 Function	Pin Number
GND	AK18
GND	AK2
GND	AK23
GND	AK29
GND	AK8
GND	B1
GND	B2
GND	B22
GND	B29
GND	B30
GND	B9
GND	C10
GND	C15
GND	C16
GND	C21
GND	C28
GND	C3
GND	D27
GND	D28
GND	D4
GND	E26
GND	E5
GND	H1
GND	H30
GND	J2
GND	J22
GND	J29
GND	J9
GND	K10
GND	K21
GND	K28
GND	K3
GND	L11
GND	L20
GND	M12

FG896	
AX2000 Function	Pin Number
GND	M13
GND	M14
GND	M15
GND	M16
GND	M17
GND	M18
GND	M19
GND	N1
GND	N12
GND	N13
GND	N14
GND	N15
GND	N16
GND	N17
GND	N18
GND	N19
GND	N30
GND	P12
GND	P13
GND	P14
GND	P15
GND	P16
GND	P17
GND	P18
GND	P19
GND	R12
GND	R13
GND	R14
GND	R15
GND	R16
GND	R17
GND	R18
GND	R19
GND	R28
GND	R3

FG896	
AX2000 Function	Pin Number
GND	T12
GND	T13
GND	T14
GND	T15
GND	T16
GND	T17
GND	T18
GND	T19
GND	T28
GND	T3
GND	U12
GND	U13
GND	U14
GND	U15
GND	U16
GND	U17
GND	U18
GND	U19
GND	V1
GND	V12
GND	V13
GND	V14
GND	V15
GND	V16
GND	V17
GND	V18
GND	V19
GND	V30
GND	W12
GND	W13
GND	W14
GND	W15
GND	W16
GND	W17
GND	W18

FG1152	
AX2000 Function	Pin Number
IO155PB3F14	AC29
IO156NB3F14	AE30
IO156PB3F14	AD30
IO157NB3F14	AC26
IO157PB3F14	AB26
IO158NB3F14	AH33
IO158PB3F14	AG33
IO159NB3F14	AD27
IO159PB3F14	AC27
IO160NB3F14	AG32
IO160PB3F14	AF32
IO161NB3F15	AG31
IO161PB3F15	AF31
IO162NB3F15	AF29
IO162PB3F15	AE29
IO163NB3F15	AE28
IO163PB3F15	AD28
IO164NB3F15	AG30
IO164PB3F15	AF30
IO165NB3F15	AE26
IO165PB3F15	AD26
IO166NB3F15	AJ30
IO166PB3F15	AH30
IO167NB3F15	AG28
IO167PB3F15	AF28
IO168NB3F15	AF27
IO168PB3F15	AE27
IO169NB3F15	AH29
IO169PB3F15	AG29
IO170NB3F15	AD25
IO170PB3F15	AC25
Bank 4	
IO171NB4F16	AP29
IO171PB4F16	AN29
IO172NB4F16	AH26

FG1152	
AX2000 Function	Pin Number
IO172PB4F16	AH27
IO173NB4F16	AJ27
IO173PB4F16	AJ28
IO174NB4F16	AL27
IO174PB4F16	AL28
IO175NB4F16	AM28
IO175PB4F16	AM29
IO176NB4F16	AG25
IO176PB4F16	AG26
IO177NB4F16	AK26
IO177PB4F16	AK27
IO178NB4F16	AF25
IO178PB4F16	AE25
IO179NB4F16	AP28
IO179PB4F16	AN28
IO180NB4F16	AJ25
IO180PB4F16	AJ26
IO181NB4F17	AM26
IO181PB4F17	AM27
IO182NB4F17	AF24
IO182PB4F17	AE24
IO183NB4F17	AH24
IO183PB4F17	AH25
IO184NB4F17	AG23
IO184PB4F17	AG24
IO185NB4F17	AL25
IO185PB4F17	AL26
IO186NB4F17	AP25
IO186PB4F17	AP26
IO187NB4F17	AK24
IO187PB4F17	AK25
IO188NB4F17	AF23
IO188PB4F17	AE23
IO189NB4F17	AN24
IO189PB4F17	AM24

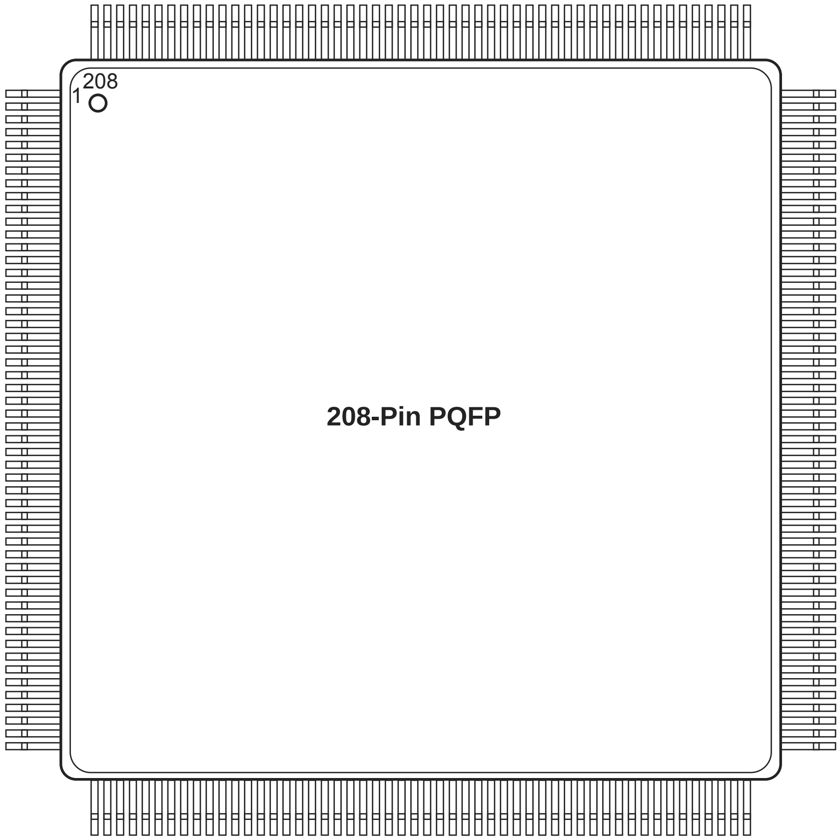
FG1152	
AX2000 Function	Pin Number
IO190NB4F17	AH22
IO190PB4F17	AH23
IO191NB4F17	AJ23
IO191PB4F17	AJ24
IO192NB4F17	AG21
IO192PB4F17	AG22
IO193NB4F18	AP23
IO193PB4F18	AP24
IO194NB4F18	AN22
IO194PB4F18	AN23
IO195NB4F18	AM23
IO195PB4F18	AL23
IO196NB4F18	AF21
IO196PB4F18	AF22
IO197NB4F18	AL22
IO197PB4F18	AM22
IO198NB4F18	AE21
IO198PB4F18	AE22
IO199NB4F18	AJ21
IO199PB4F18	AJ22
IO200NB4F18	AK21
IO200PB4F18	AK22
IO201NB4F18	AM21
IO201PB4F18	AL21
IO202NB4F18	AE20
IO202PB4F18	AD20
IO203NB4F19	AN21
IO203PB4F19	AP21
IO204NB4F19	AP20
IO204PB4F19	AN20
IO205NB4F19	AN19
IO205PB4F19	AP19
IO206NB4F19	AG20
IO206PB4F19	AF20
IO207NB4F19	AL19

FG1152	
AX2000 Function	Pin Number
IO311NB7F29	N3
IO311PB7F29	P3
IO312NB7F29	P7
IO312PB7F29	R7
IO313NB7F29	P6
IO313PB7F29	R6
IO314NB7F29	M2
IO314PB7F29	N2
IO315NB7F29	N4
IO315PB7F29	P4
IO316NB7F29	R9
IO316PB7F29	R8
IO317NB7F29	N5
IO317PB7F29	P5
IO318NB7F29	R10
IO318PB7F29	R11
IO319NB7F29	L2
IO319PB7F29	L1
IO320NB7F29	N8
IO320PB7F29	P8
IO321NB7F30	M6
IO321PB7F30	N6
IO322NB7F30	P10
IO322PB7F30	P9
IO323NB7F30	L3
IO323PB7F30	M3
IO324NB7F30	M7
IO324PB7F30	N7
IO325NB7F30	K2
IO325PB7F30	K1
IO326NB7F30	G2
IO326PB7F30	H2
IO327NB7F30	L6
IO327PB7F30	L5
IO328NB7F30	N10

FG1152	
AX2000 Function	Pin Number
IO328PB7F30	N9
IO329NB7F30	J4
IO329PB7F30	K4
IO330NB7F30	J5
IO330PB7F30	K5
IO331NB7F30	M10
IO331PB7F30	M9
IO332NB7F31	L8
IO332PB7F31	M8
IO333NB7F31	F2
IO333PB7F31	F1
IO334NB7F31	J6
IO334PB7F31	K6
IO335NB7F31	H4
IO335PB7F31	H3
IO336NB7F31	K7
IO336PB7F31	L7
IO337NB7F31	G4
IO337PB7F31	G3
IO338NB7F31	K9
IO338PB7F31	L9
IO339NB7F31	H6
IO339PB7F31	H5
IO340NB7F31	H7
IO340PB7F31	J7
IO341NB7F31	J8
IO341PB7F31	K8
Dedicated I/O	
GND	A13
GND	A2
GND	A22
GND	A27
GND	A3
GND	A31
GND	A32

FG1152	
AX2000 Function	Pin Number
GND	A33
GND	A4
GND	A8
GND	AA14
GND	AA15
GND	AA16
GND	AA17
GND	AA18
GND	AA19
GND	AA20
GND	AA21
GND	AB1
GND	AB13
GND	AB22
GND	AB34
GND	AC12
GND	AC23
GND	AC30
GND	AC5
GND	AD11
GND	AD24
GND	AD31
GND	AD4
GND	AE3
GND	AE32
GND	AF2
GND	AF33
GND	AG1
GND	AG27
GND	AG34
GND	AG8
GND	AH28
GND	AH7
GND	AJ29
GND	AJ6

PQ208



Note

For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

PQ208	
AX500 Function	Pin Number
Bank 0	
IO03NB0F0	198
IO03PB0F0	199
IO04NB0F0	197
IO19NB0F1/HCLKAN	191
IO19PB0F1/HCLKAP	192
IO20NB0F1/HCLKBN	185
IO20PB0F1/HCLKBP	186
Bank 1	
IO21NB1F2/HCLKCN	180
IO21PB1F2/HCLKCP	181
IO22NB1F2/HCLKDN	174
IO22PB1F2/HCLKDP	175
IO23NB1F2	170
IO23PB1F2	171
IO37NB1F3	165
IO37PB1F3	166
IO39NB1F3	161
IO39PB1F3	162
IO41NB1F3	159
IO41PB1F3	160
Bank 2	
IO43NB2F4	151
IO43PB2F4	153
IO44NB2F4	152
IO44PB2F4	154
IO45PB2F4	148
IO46NB2F4	146
IO46PB2F4	147
IO48NB2F4	144
IO48PB2F4	145
IO57NB2F5	139
IO57PB2F5	140
IO58PB2F5	141
IO59NB2F5	137
IO59PB2F5	138
IO61NB2F5	132

PQ208	
AX500 Function	Pin Number
IO61PB2F5	134
IO62NB2F5	131
IO62PB2F5	133
Bank 3	
IO63NB3F6	127
IO63PB3F6	129
IO64NB3F6	126
IO64PB3F6	128
IO66NB3F6	122
IO66PB3F6	123
IO68NB3F6	120
IO68PB3F6	121
IO77NB3F7	116
IO77PB3F7	117
IO79NB3F7	114
IO79PB3F7	115
IO81NB3F7	110
IO81PB3F7	111
IO82NB3F7	108
IO82PB3F7	109
IO83NB3F7	106
IO83PB3F7	107
Bank 4	
IO84PB4F8	103
IO85NB4F8	100
IO86NB4F8	101
IO86PB4F8	102
IO87NB4F8	96
IO87PB4F8	97
IO101NB4F9	91
IO101PB4F9	92
IO103NB4F9/CLKEN	87
IO103PB4F9/CLKEP	88
IO104NB4F9/CLKFN	81
IO104PB4F9/CLKFP	82
Bank 5	
IO105NB5F10/CLKGN	76

PQ208	
AX500 Function	Pin Number
IO105PB5F10/CLKGP	77
IO106NB5F10/CLKHN	70
IO106PB5F10/CLKHP	71
IO107NB5F10	66
IO107PB5F10	67
IO119NB5F11	62
IO121NB5F11	60
IO121PB5F11	61
IO123NB5F11	56
IO123PB5F11	57
IO125NB5F11	54
IO125PB5F11	55
Bank 6	
IO127NB6F12	47
IO127PB6F12	49
IO128NB6F12	48
IO128PB6F12	50
IO129NB6F12	42
IO129PB6F12	43
IO130PB6F12	44
IO132NB6F12	40
IO132PB6F12	41
IO141NB6F13	35
IO141PB6F13	36
IO142PB6F13	37
IO143NB6F13	33
IO143PB6F13	34
IO145NB6F13	28
IO145PB6F13	30
IO146NB6F13	27
IO146PB6F13	29
Bank 7	
IO147NB7F14	23
IO147PB7F14	25
IO148NB7F14	22
IO148PB7F14	24
IO150NB7F14	18

CG624	
AX2000 Function	Pin Number
GND	M11
GND	M12
GND	M13
GND	M14
GND	M15
GND	N11
GND	N12
GND	N13
GND	N14
GND	N15
GND	P11
GND	P12
GND	P13
GND	P14
GND	P15
GND	R11
GND	R12
GND	R13
GND	R14
GND	R15
GND	T21
GND	T23
GND	T3
GND	T5
GND	V1
GND	V25
GND	V5
PRA	F13
PRB	A13
PRC	AB12
PRD	AE13
TCK	F5

Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.

CG624	
AX2000 Function	Pin Number
TDI	C5
TDO	F6
TMS	D6
TRST	E6
VCCA	AB20
VCCA	F22
VCCA	F4
VCCA	J17
VCCA	J9
VCCA	K10
VCCA	K11
VCCA	K15
VCCA	K16
VCCA	L10
VCCA	L16
VCCA	R10
VCCA	R16
VCCA	T10
VCCA	T11
VCCA	T15
VCCA	T16
VCCA	U17
VCCA	U9
VCCA	Y4
VCCDA	A12
VCCDA	A14
VCCDA	AA13
VCCDA	AA15
VCCDA	AA20
VCCDA	AA7
VCCDA	AB13
VCCDA	AC11

Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.

CG624	
AX2000 Function	Pin Number
VCCDA	AD11
VCCDA	AD4
VCCDA	AE12
VCCDA	AE17
VCCDA	B15
VCCDA	C15
VCCDA	C6
VCCDA	D13
VCCDA	E13
VCCDA	E19
VCCDA	F21
VCCDA	G10
VCCDA	G5
VCCDA	N21
VCCDA	N5
VCCDA	W21
VCCIB0	A3
VCCIB0	B3
VCCIB0	C4
VCCIB0	D5
VCCIB0	J10
VCCIB0	J11
VCCIB0	K12
VCCIB1	A23
VCCIB1	B23
VCCIB1	C22
VCCIB1	D21
VCCIB1	J15
VCCIB1	J16
VCCIB1	K14
VCCIB2	C24
VCCIB2	C25

Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.